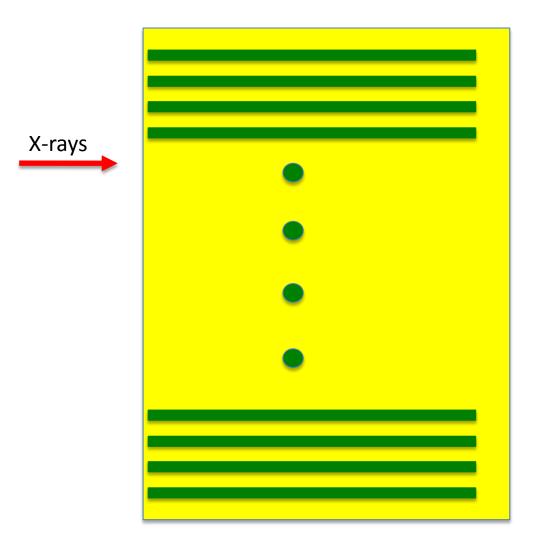
Thin Active Edges

Each sensor chip is 50 μ m thick Each sensor is about 2 mm "deep" Would need to stack 10 high to cover 500 μ m Summed strip capacitance to backside is about 1 pF Inter-strip capacitance should be 1-2 pF for a total of 3 pF

Thin Active Edges



Each sensor has 128 or more strips Strip pitch between 25 and 50 μm

Could stagger alternating sensors by half the pitch to improve spatial resolution

Main pitch limitation is wire bonding

Thin Active Edges

If divergence is small and sensors well aligned the photon paths, then could make do with one sensor size.